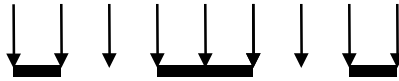


# Microlithography

Clean Wafer



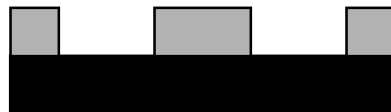
Photoresist Applied



Exposure



Development



Etching



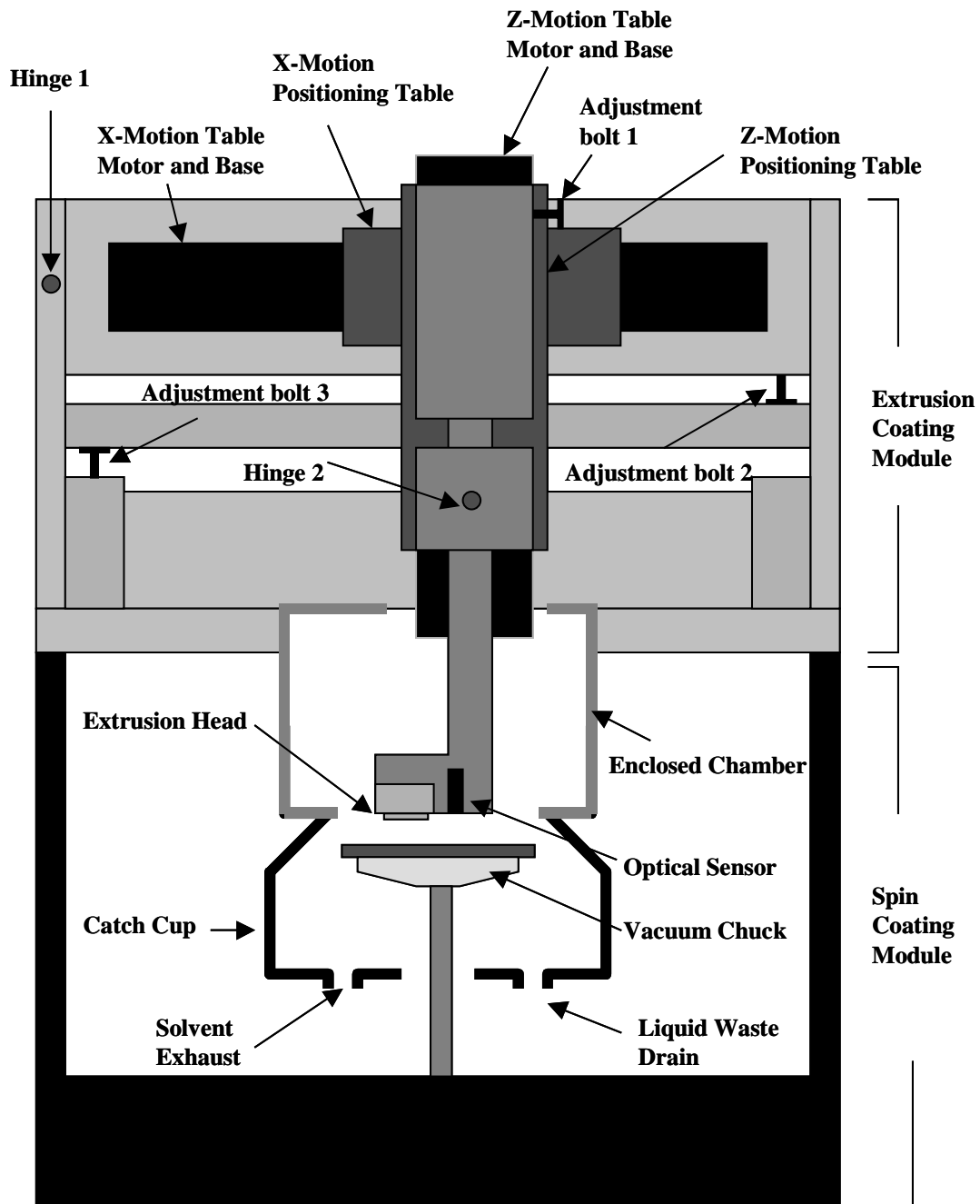
Clean Wafer



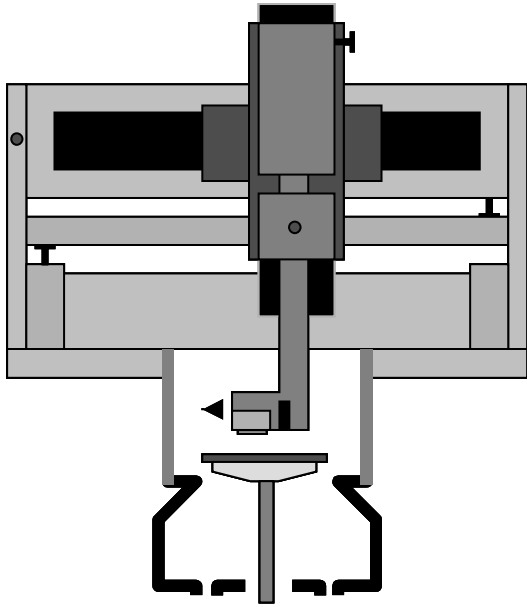
Positive photoresist

Negative photoresist 1

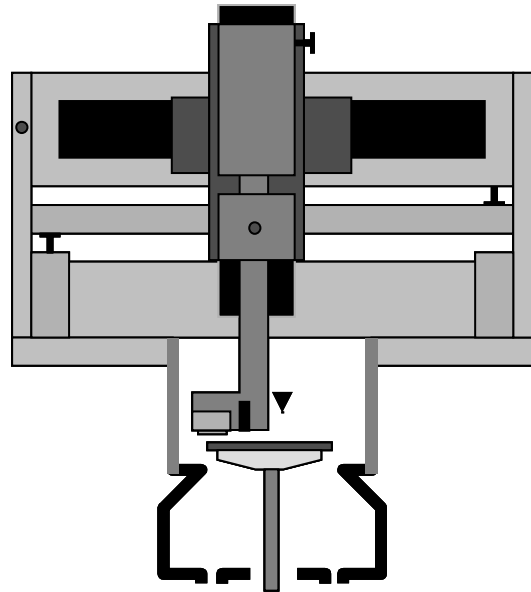
# EXPERIMENTAL APPARATUS



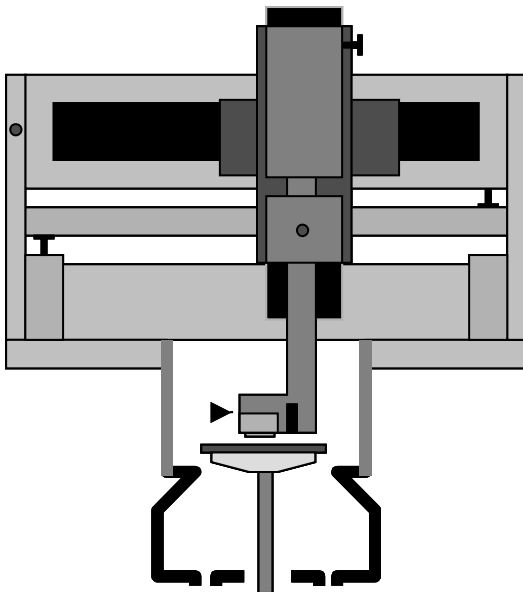
# Operation of Extrusion-Spin Coater



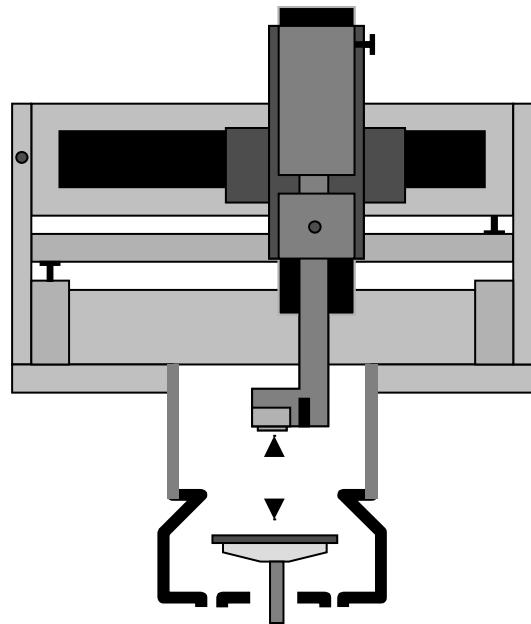
(a) Scanning wafer surface



(b) Locating the coating outset position



(c) Applying photoresist to the wafer using extrusion coating



(d) End of extrusion coating  
Spin coating initiates